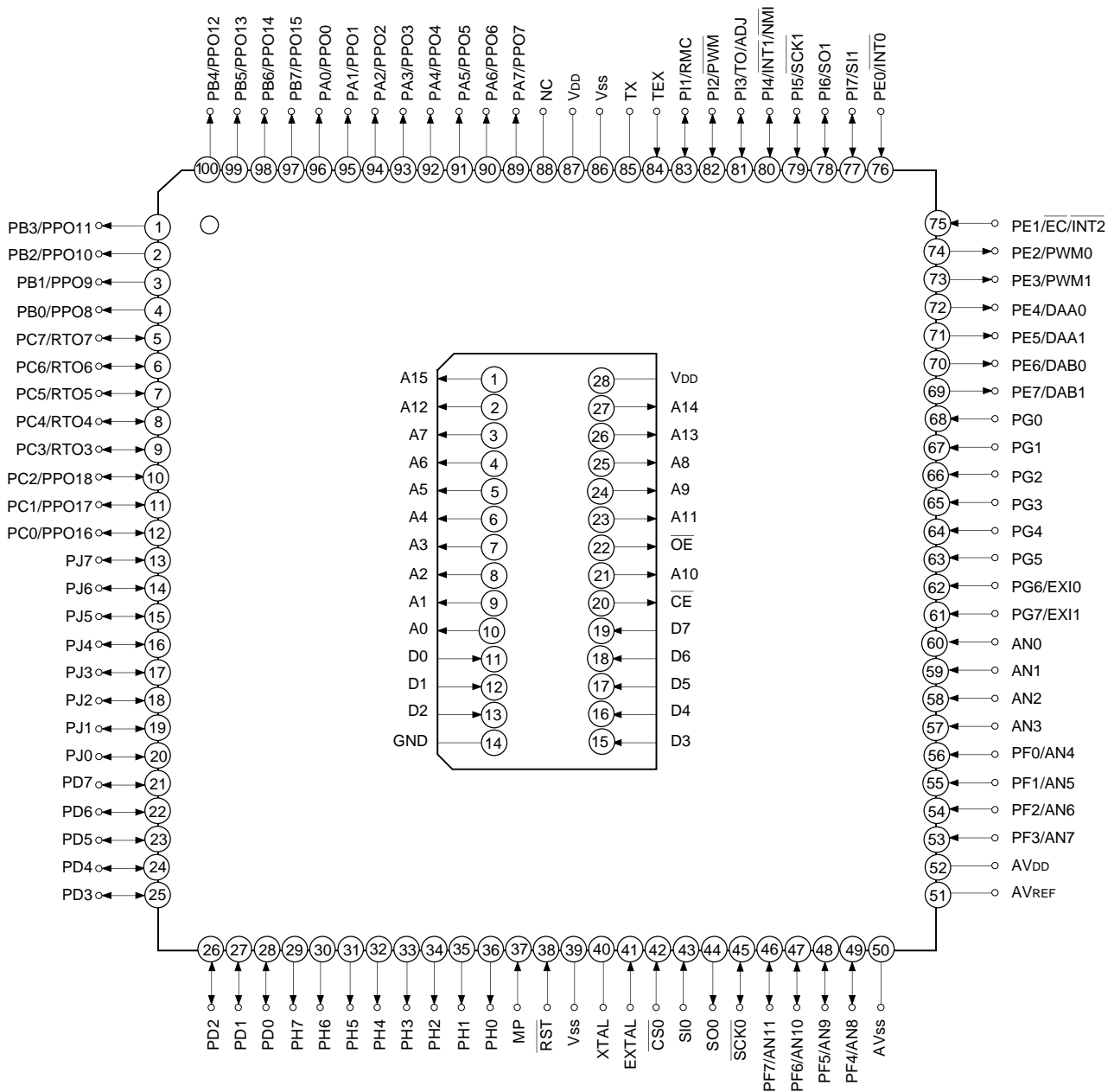
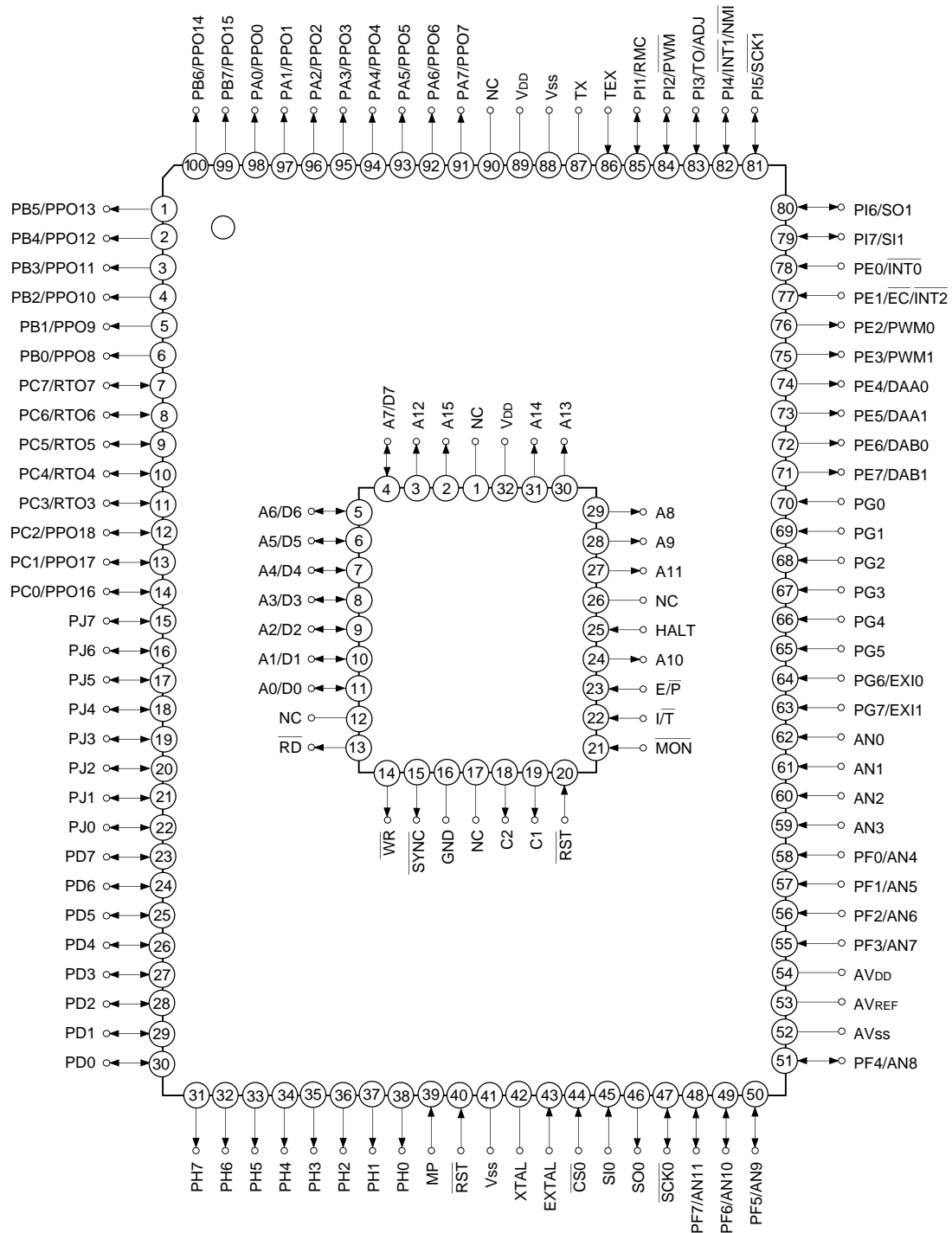


Pin Configuration in Piggyback Mode (LQFP package)



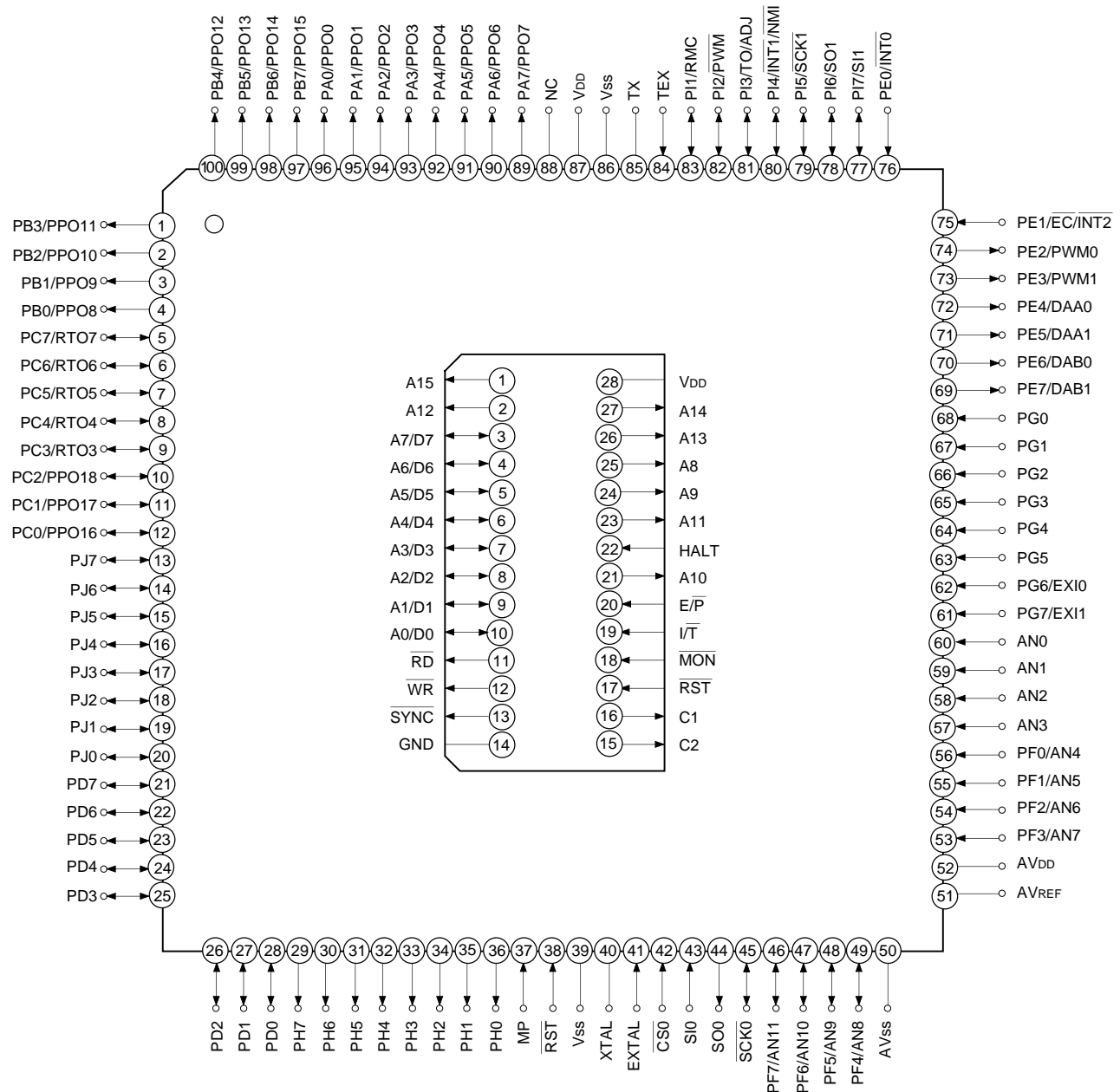
- Note)**
1. NC (Pin 88) is always connected to VDD.
 2. VSS (Pins 39 and 86) are both connected to GND.
 3. MP (Pin 37) is always connected to GND.

Pin Configuration in Evaluator Mode (QFP package)



- Note)**
1. NC (Pin 90) is always connected to VDD.
 2. Vss (Pins 41 and 88) are both connected to GND.
 3. MP (Pin 39) is always connected to GND.

Pin Configuration in Evaluator Mode (LQFP package)



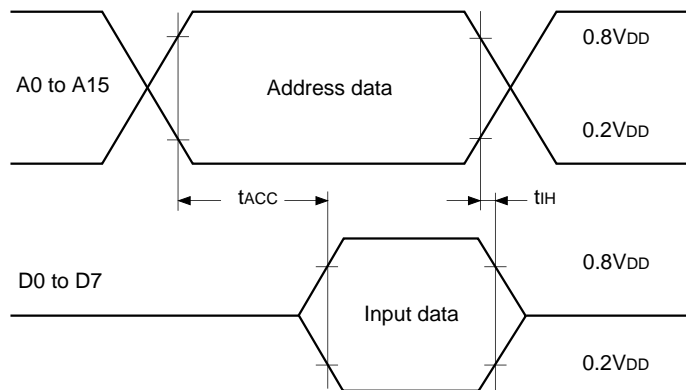
- Note**
1. NC (Pin 88) is always connected to V_{DD}.
 2. V_{SS} (Pins 39 and 86) are both connected to GND.
 3. MP (Pin 37) is always connected to GND.

EPROM Read Timing ($T_a = -20$ to $+75^\circ\text{C}$, $V_{DD} = 3.0$ to 5.5V , $V_{SS} = 0\text{V}$)

Item	Symbol	Pin	Min.	Max.	Unit
Address → data input delay time	t_{ACC}	A0 to A15 D0 to D7		100*1	ns
				75*2	
Address → data hold time	t_{IH}	A0 to A15 D0 to D7	0		ns

*1 At 12MHz operation ($V_{DD} = 4.5$ to 5.5V)

*2 At 12MHz operation ($V_{DD} = 3.0$ to 5.5V), At 16MHz operation ($V_{DD} = 4.5$ to 5.5V)

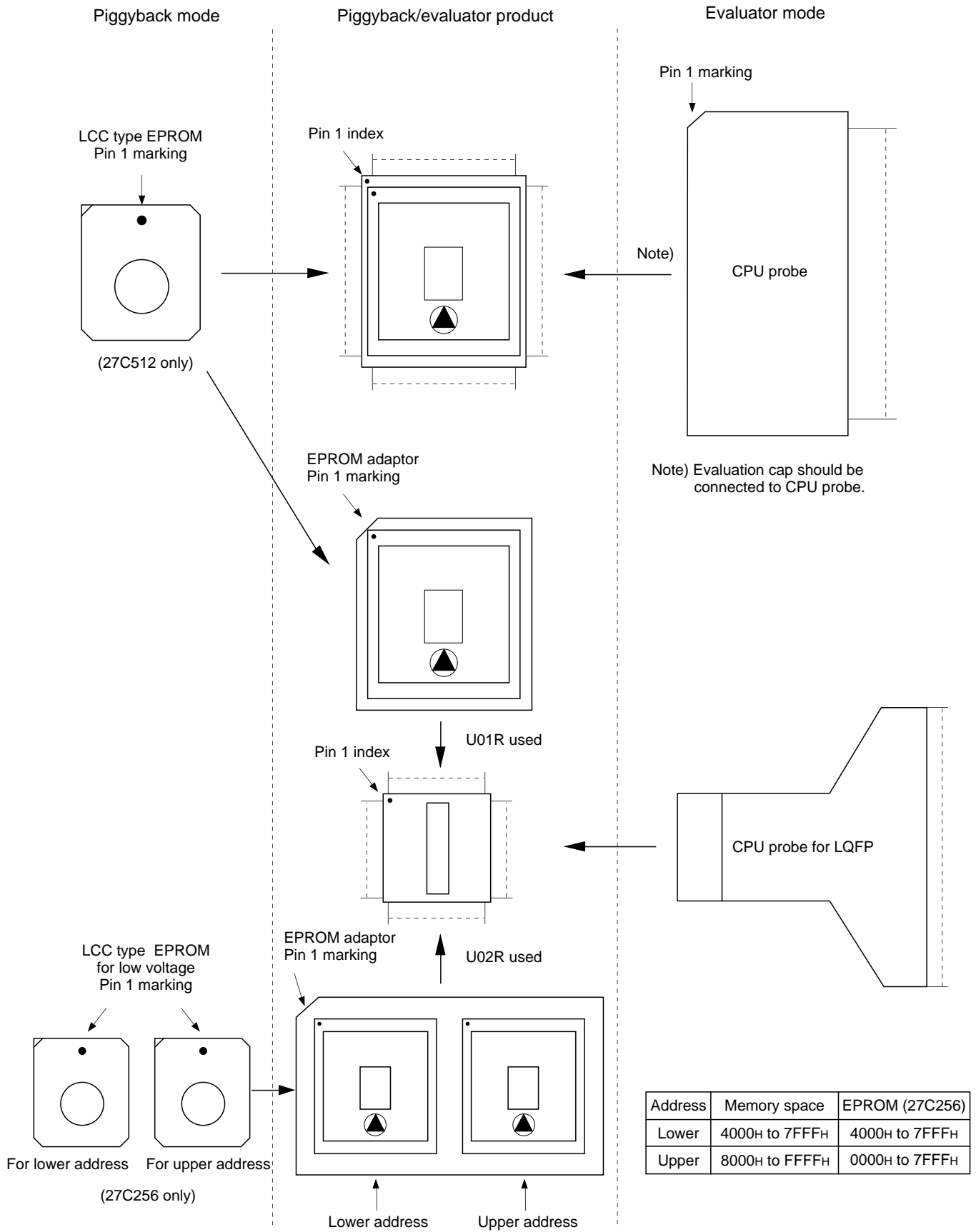


Products List

Optional item	Products			
	Mask product		Piggyback/evaluator product	
	CXP81840A	CXP81848A	CXP81800-U01Q CXP81800-U01R	CXP81800-U02R
Package	100-pin plastic QFP/LQFP		100-pin ceramic PQFP	
ROM capacitance	40Kbytes	48Kbytes	EPROM 48Kbytes	
			27C512 × 1	27C256 × 2
Pull-up resistance for reset pin	Existent/Non-existent		Existent	
Input circuit format*1	CMOS schmitt/TTL schmitt		TTL schmitt	CMOS schmitt

*1 On PG4 pin and PG5 pin, the input circuit format can be selected to every pin.

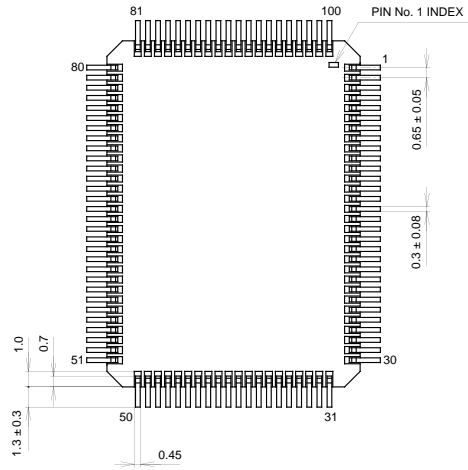
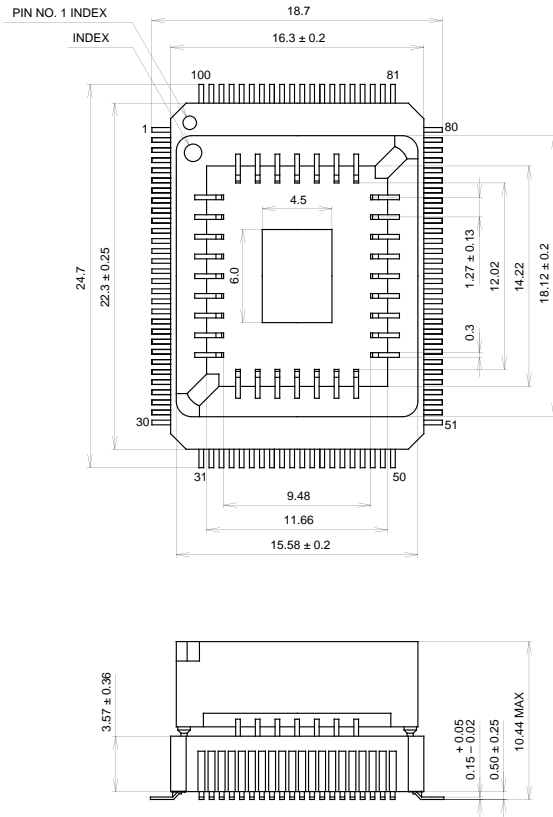
Piggyback mode/evaluator mode can be switched as shown below



Package Outline

Unit: mm

100PIN PQFP (CERAMIC)

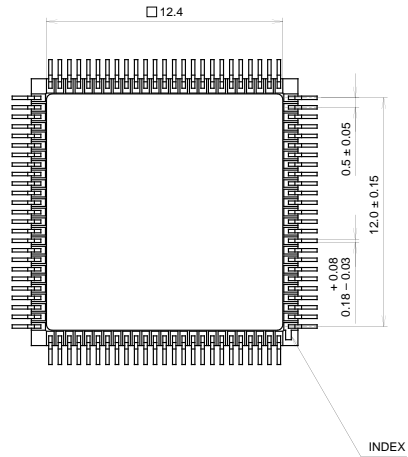
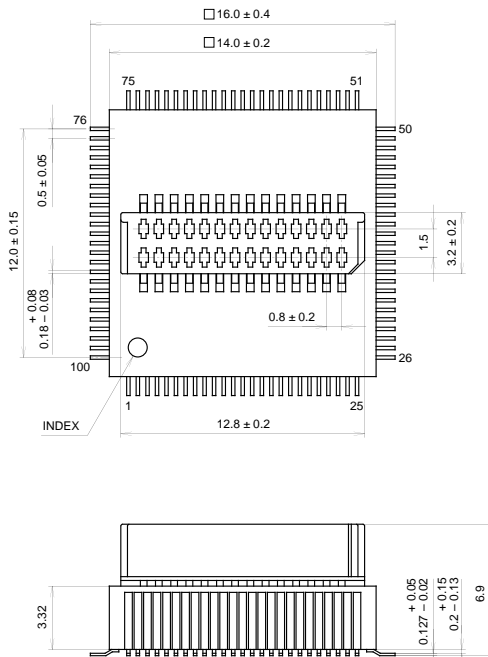


PACKAGE STRUCTURE

SONY CODE	PQFP-100C-L01
EIAJ CODE	AQFP100-C-0000-A
JEDEC CODE	

PACKAGE MATERIAL	CERAMIC
LEAD TREATMENT	GOLD PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	5.7g

100PIN PQFP (CERAMIC)



PACKAGE STRUCTURE

SONY CODE	PQFP-100C-L02
EIAJ CODE	AQFP100-C-1414-A
JEDEC CODE	

PACKAGE MATERIAL	CERAMIC
LEAD TREATMENT	GOLD PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	2.2g